

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7210667

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LIANGPING MA	11/03/2021
XIAO FENG WANG	10/19/2021
ALBERTO RICO ALVARINO	10/18/2021
UMESH PHUYAL	10/11/2021
JUN MA	10/15/2021
AYAN SENGUPTA	10/11/2021
JUAN MONTOJO	10/10/2021
PETER GAAL	10/13/2021
WANSHI CHEN	10/22/2021
BHARAT SHRESTHA	11/01/2021
CHANGHWAN PARK	10/10/2021
HUILIN XU	10/29/2021

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17653715

CORRESPONDENCE DATA

Fax Number: (571)432-0808

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5714320808

Email: cbrandt@harrityllp.com

Correspondent Name: HARRITY & HARRITY, LLP

Address Line 1: 11350 RANDOM HILLS ROAD

Address Line 2: SUITE 600

PATENT

Address Line 4: FAIRFAX, VIRGINIA 22030

ATTORNEY DOCKET NUMBER: 2104820C1

NAME OF SUBMITTER: /JENNY ROSENFELD/

SIGNATURE: /JENNY ROSENFELD/

DATE SIGNED: 03/07/2022

Total Attachments: 14

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ASSIGNMENT

WHEREAS, WE,

1. **Liangping MA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
2. **Xiao Feng WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
3. **Alberto RICO ALVARINO**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
4. **Umesh PHUYAL**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
5. **Jun MA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
6. **Ayan SENGUPTA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
7. **Juan MONTOJO**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
8. **Peter GAAL**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
9. **Wanshi CHEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
10. **Bharat SHRESTHA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
11. **Changhwan PARK**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
12. **Huilin XU**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **TIMING OFFSET SELECTION IN NON-TERRESTRIAL NETWORK** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and

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interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s). 17/449,507** filed **September 30, 2021, Qualcomm Reference Number 2104820**, and all provisional applications relating thereto, together with **U.S. Provisional Application No(s). 63/187,314** filed **May 11, 2021, Qualcomm Reference Number 2104820P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;


AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States

on 11/3/2021




City, State, Country


Date

Liangping MA


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 10/19/2021 
City, State, Country Date Xiao Feng WANG

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

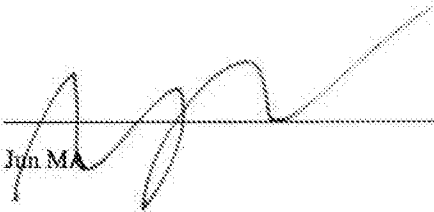
Done at San Diego, CA, United States on 10/18/21
City, State, Country Date 
Alberto RICO ALVARINO

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.


Done at San Diego, CA, United States on 10/11/2021 
City, State, Country Date Umesh PHUYAL

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 10/15/21
City, State, Country Date

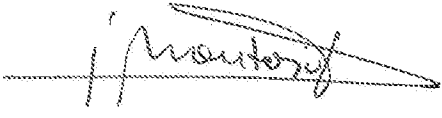

Jun MA

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 10/11/2021 
City, State, Country Date Ayan SENGUPTA

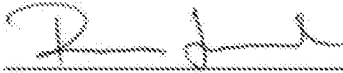
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 10/10/21
City, State, Country Date

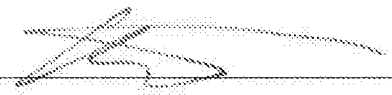


Juan MONTOJO

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

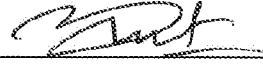
Done at San Diego, CA, United States on 10/13/2021 
City, State, Country Date Peter GAAL

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

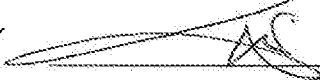
Beijing China
CWC
San Diego, CA, United States
Done at _____ on 1/22/2024 

City, State, Country Date Wanshi CHEN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 11/01/2021 
City, State, Country Date Bharat SHRESTHA

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on Oct. 10, 2021 
City, State, Country Date Changhwan PARK

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Temecula, CA, United States on 10/29/2024 HOU
City, State, Country Date Huilin XU